

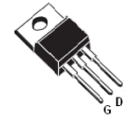
## 650V N-Channel Super Junction power MOSFET

### DESCRIPTION

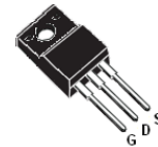
SJ MOSFET is an advanced technology for high voltage power MOSFETs, designed according to the super junction principle by Xinyuan semiconductor. The offered devices provide all benefits of a fast switching and low on resistance, making it especially suitable for applications which require more efficient, more compact, lighter, High Performance Adapter etc.

$V_{DS}$	650	V
$R_{DS(ON)}$	70	m $\Omega$
$I_D$	47	A

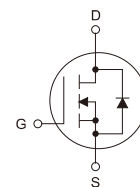
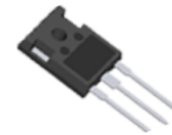
TO-220



TO-220F



TO-247



### Features

- Extremely low losses due to very low  $R_{dson} * Q_g$
- Superior Avalanche Rugged Technology
- Fast switching capability
- 100% Avalanche Tested
- Pb-free lead plating; ROHS compliant

### APPLICATIONS

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- High Performance Adapter
- LED Lighting Power

### ORDERING INFORMATION

Temperature Range	Package		Orderable Device	Package Qty.
-55°C ~ +125°C	TO-220	Pb-Free	CWH65R070AC	50 PCS/Tube
	TO-220F		CWH65R070AF	50 PCS/Tube
	TO-247		CWH65R070AZ	30 PCS/Tube



## ABSOLUTE MAXIMUM RATINGS

( $T_j=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	$V_{DSS}$	650	V
Gate-Source Voltage ( $V_{DS}=0\text{V}$ , static)	$V_{GS}$	$\pm 30$	V
Continuous Drain Current( $T_C=25^{\circ}\text{C}$ )(Note1)	$I_{D(DC)}$	47	A
Continuous Drain Current( $T_C=100^{\circ}\text{C}$ )(Note1)	$I_{D(DC)}$	30	A
Pulsed Drain Current(Note2)	$I_{DM}$	140	A
MOSFET dv/dt ruggedness, $V_{DS}\leq 480\text{V}$	dv/dt	50	V/nS
Single Pulsed Avalanche Energy(Note3)	$E_{AS}$	1440	mJ
Avalanche Energy, Repetitive(Note1)	$E_{AR}$	2	mJ
Avalanche Current, Repetitive(Note1)	$I_{AS}$	17	A
Maximum Power Dissipation ( $T_C=25^{\circ}\text{C}$ )	$P_D$	TO-220: 219 TO-220F: 34 TO-247: 280	W
Operating, Storage Temperature Range	$T_J, T_{STG}$	-55~150	$^{\circ}\text{C}$

## THERMAL CHARACTERISTICS

Parameter	Symbol	Min.	Typ.	Max.	Units
Thermal Resistance, Junction-to-Case	$R_{thJC}$	-	-	TO-220: 0.57 TO-220F: 3.65 TO-247: 0.45	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	-	-	TO-220: 62 TO-220F: 80 TO-247: 62	$^{\circ}\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS

( $T_j=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	TYP.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0\text{V}, I_D=1\text{mA}$	650	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=650\text{V}, V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30\text{V}, V_{DS}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=1\text{mA}$	2.0	3.0	4.0	V
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=23.5\text{A}$	-	0.065	0.07	$\Omega$
Gate Resistance	$R_g$	F=1MHZ, open drain	-	7.36	-	$\Omega$



## Dynamic Characteristics

( $T_j = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input capacitance	$C_{iss}$	$V_{DS}=100\text{V}, V_{GS}=0\text{V},$ $f=1\text{MHz}$	-	3500	-	pF
Output capacitance	$C_{oss}$		-	138	-	
Reverse transfer capacitance	$C_{rss}$		-	5.0	-	
Turn-on delay Time	$t_{d(on)}$	$V_{DD}=400\text{V}, I_D=23.5\text{A}$ $R_G=3.3\Omega, V_{GS}=10\text{V}$	-	59	-	ns
Rise time	$t_r$		-	56		
Turn-off delay time	$t_{d(off)}$		-	360		
Fall time	$t_f$		-	57		

## Gate charge characteristics

( $T_j = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Gate to Source Charge	$Q_{gs}$	$V_{DD}=400\text{V}, I_D=23.5\text{A}$ $V_{GS}=0 \text{ to } 10\text{V}$	-	20.9	-	nC
Gate to Drain Charge	$Q_{gd}$		-	16.3	-	
Gate Charge Total	$Q_g$		-	65.2	-	
Gate Plateau Voltage	$V_{plateau}$		-	5.6	-	V

## Reverse diode characteristics

( $T_j = 25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Body Diode Forward Voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_{SD}=47\text{A}$	-	0.9	-	V
Reverse Recovery Time	$t_{rr}$	$V_R=400\text{V},$ $I_F=23.5\text{A}$ $di_F/dt=100\text{A}/\mu\text{s}$	-	452	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	8.23	-	$\mu\text{C}$
Peak Reverse Recovery Current	$I_{rrm}$		-	32.1	-	A

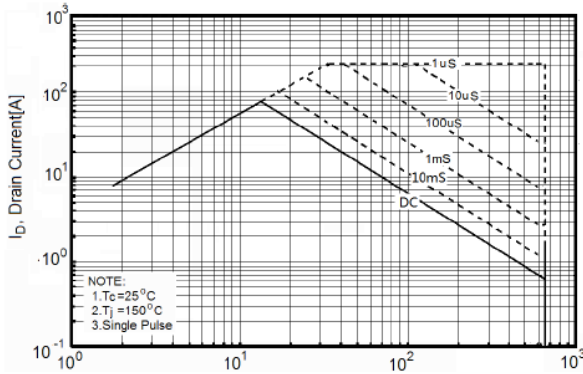
### Notes:

1. Limited by maximum junction temperature;
2. Pulse width limited by maximum junction temperature;
3.  $I_{AS} = 17\text{A}, V_{DD} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_j = 25^\circ\text{C}$ .



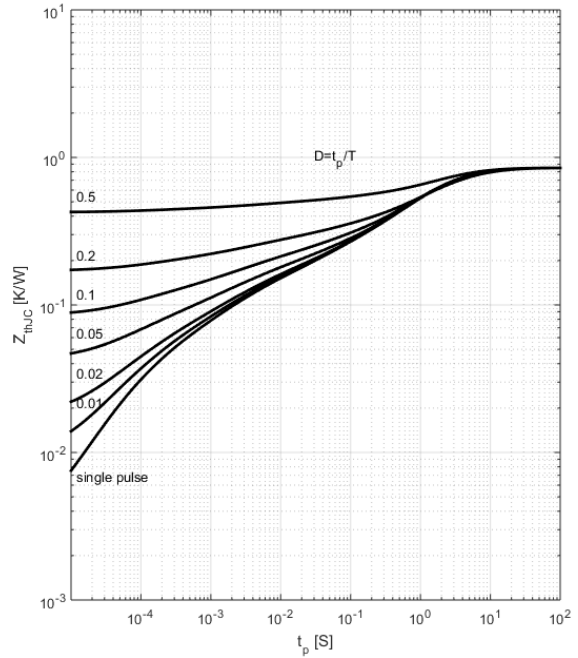
## Electrical Characteristics Diagrams

Figure 1. Safe operating area



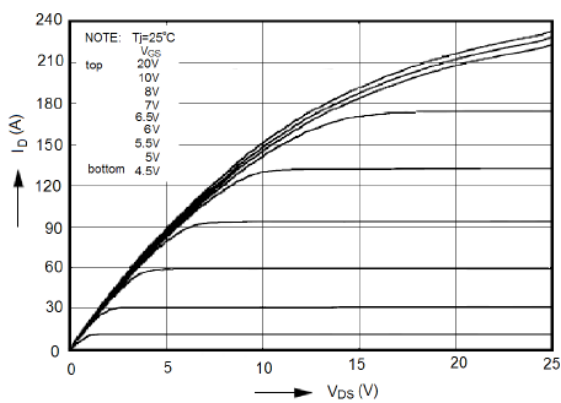
$I_D=f(V_{DS}); T_c=25^\circ\text{C};$  parameter  $t_p$

Figure2. Transient thermal impedance



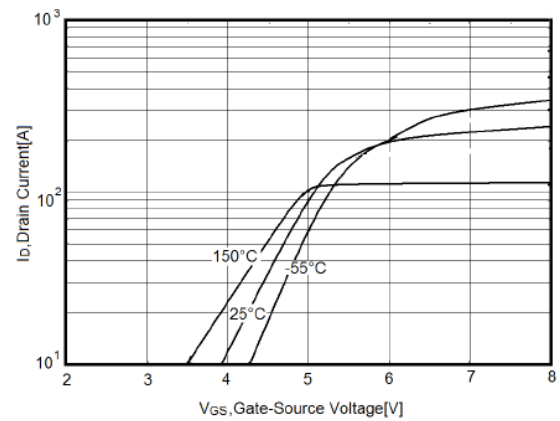
$Z_{(thJC)}=f(t_p);$  parameter:  $D=t_p/T$

Figure3. Typ. output characteristics



$I_D=f(V_{DS}); T_j=25^\circ\text{C};$  parameter:  $V_{GS}$

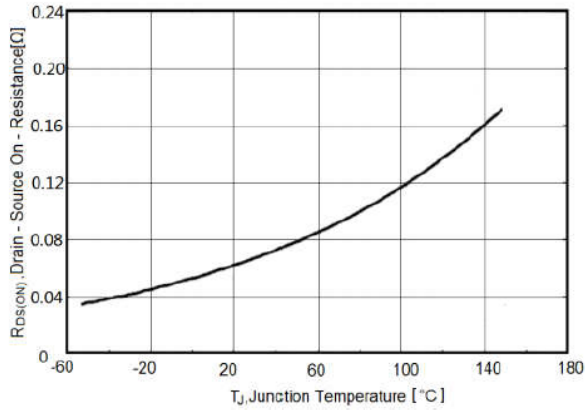
Figure 4. Typ. transfer characteristics



$I_D=f(V_{GS}); V_{DS}=20\text{V}$

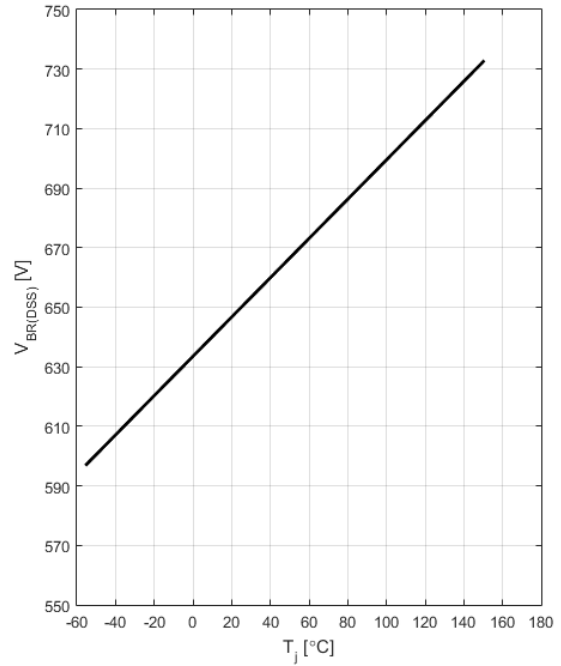


**Figure5. Drain-source on-state resistance**



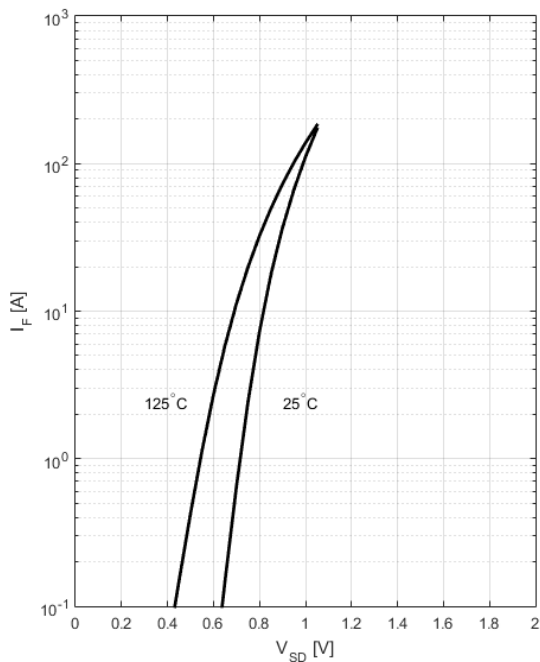
**$R_{DS(ON)}=f(T_j)$ ;  $I_D=20A$ ;  $V_{GS}=10V$**

**Figure6. Drain-source breakdown voltage**



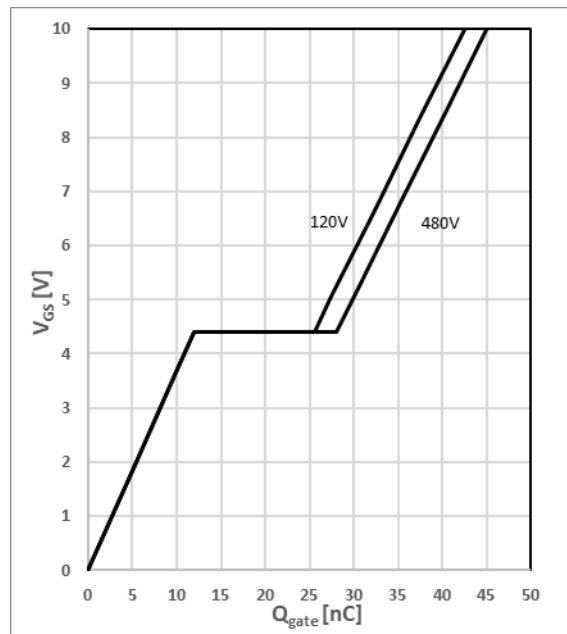
**$V_{BR(DSS)}=f(T_j)$ ;  $I_D=10mA$**

**Figure7. Forward characteristics of reverse diode**



**$I_F=f(V_{SD})$ ; parameter:  $T_j$**

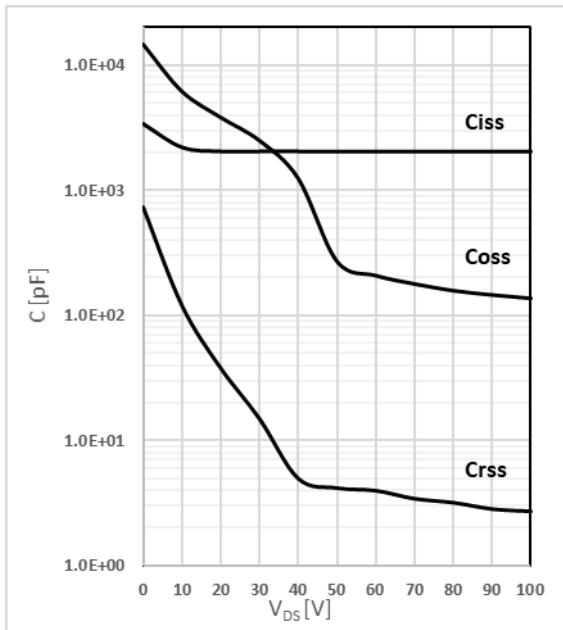
**Figure 8. Typ. gate charge**



**$V_{GS}=f(Q_{gate})$ ,  $I_D=47A$  pulsed**

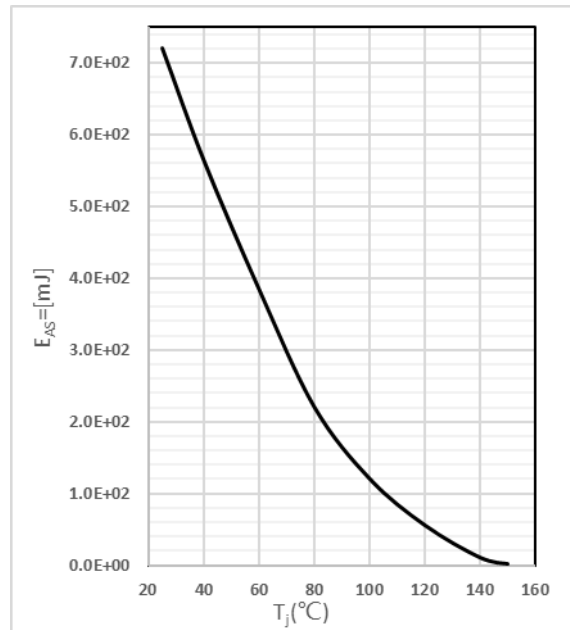


**Figure9: Typ. capacitances**



**$C=f(V_{DS}); V_{GS}=0; f=1\text{MHz}$**

**Figure10: Avalanche energy**

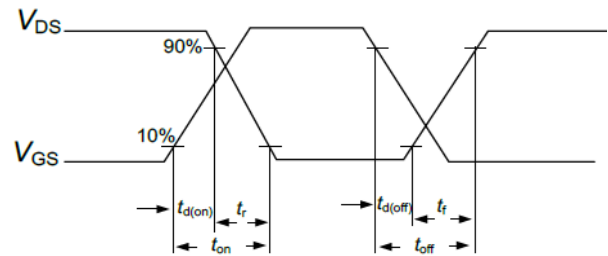
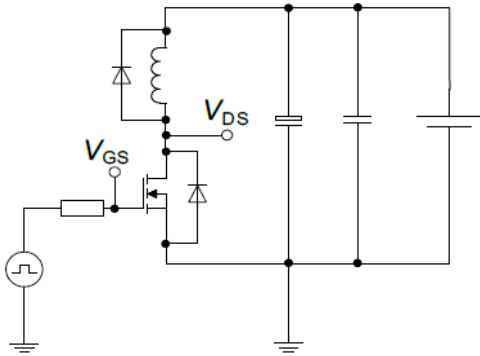


**$E_{AS}=f(T_j); I_D=16\text{A}; V_{DD}=50\text{V}$**

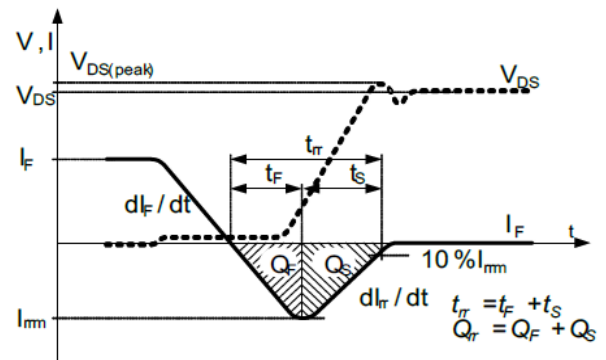
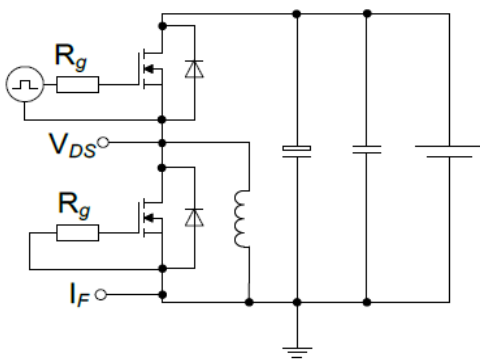


## Test Circuits

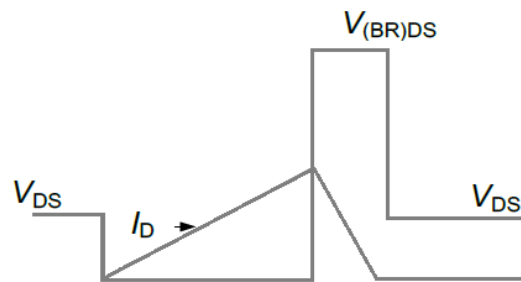
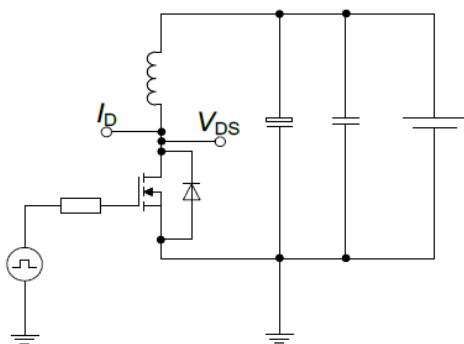
### Switch time test circuit



### Reverse diode characteristics test circuit and waveform

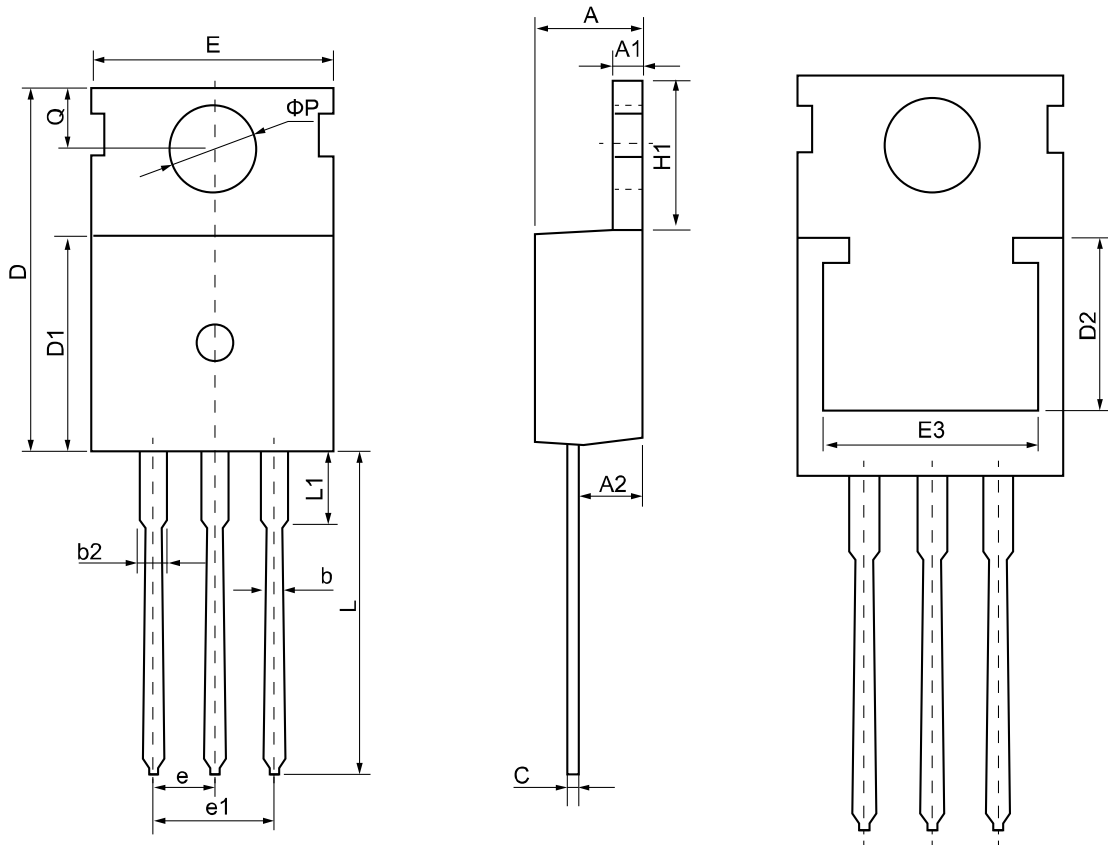


### Unclamped inductive switching test circuit & waveform



## PHYSICAL DIMENSIONS

TO-220

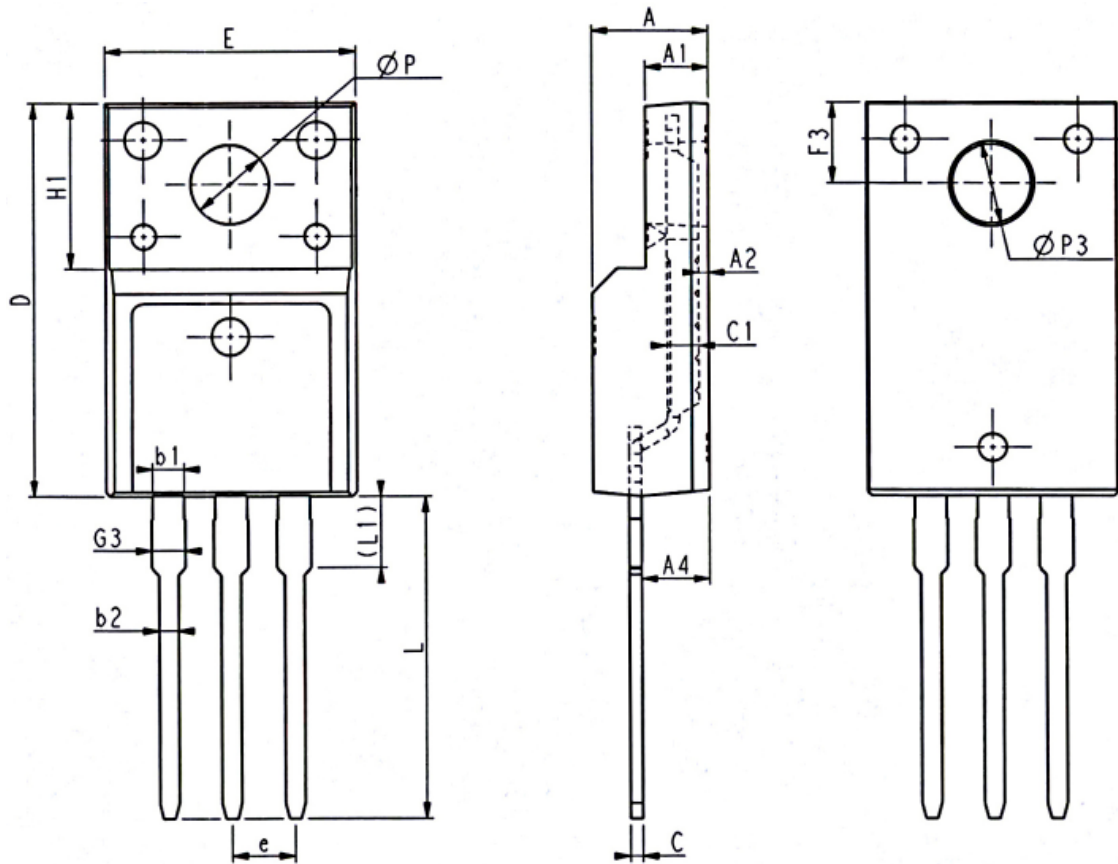


Symbol	Dimension (mm)			Symbol	Dimension (mm)		
	Min	Nom	Max		Min	Nom	Max
A	4.37	4.57	4.77	E	9.80	10.00	10.20
A1	1.25	1.30	1.45	E3	7.00	-	-
A2	2.20	2.40	2.60	e	2.54(BSC)		
b	0.70	0.80	0.95	e1	5.08(BSC)		
b2	1.17	1.27	1.47	H1	6.30	6.50	6.80
c	0.40	0.50	0.65	L	12.75	13.50	13.80
D	15.30	15.60	15.90	L1	-	3.10	3.40
D1	8.90	9.10	9.30	ΦP	3.40	3.60	3.80
D2	5.50	-	-	Q	2.60	2.80	3.00





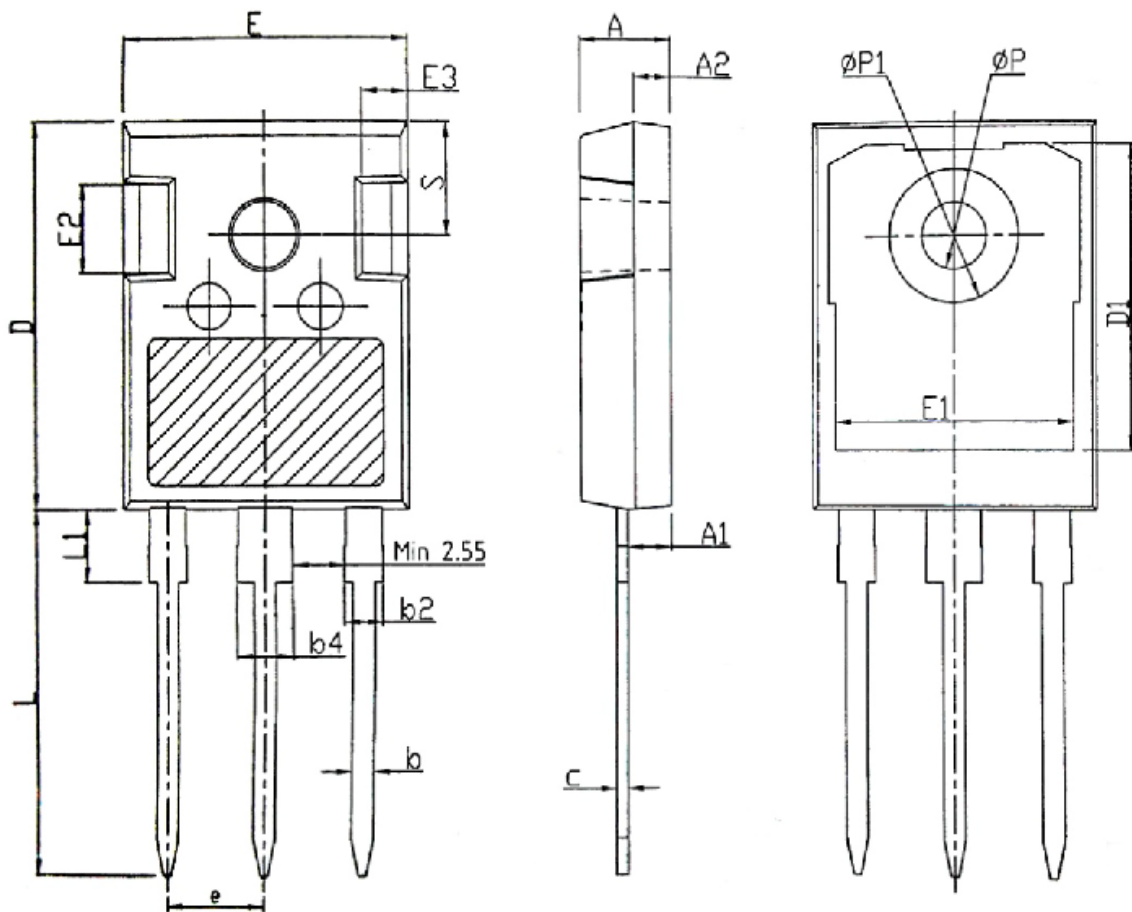
TO-220F



Symbol	Dimension (mm)			Symbol	Dimension (mm)		
	Min	Nom	Max		Min	Nom	Max
E	9.96	10.16	10.36	e	2.54(BSC)		
A	4.50	4.70	4.90	L	12.68	12.98	13.28
A1	2.34	2.54	2.74	L1	2.93	3.03	3.13
A2	0.30	0.45	0.60	$\Phi P$	3.03	3.18	3.38
A4	2.56	2.76	2.96	$\Phi P3$	3.15	3.45	3.65
c	0.40	0.50	0.65	F3	3.15	3.30	3.45
c1	1.20	1.30	1.35	G3	1.25	1.35	1.55
D	15.57	15.87	16.17	b1	1.18	1.28	1.43
H1	6.70(REF)			b2	0.70	0.80	0.95



TO-247



Symbol	Dimension (mm)			Symbol	Dimension (mm)		
	Min	Nom	Max		Min	Nom	Max
A	4.80	5.00	5.20	E1	13.00	13.30	13.60
A1	2.21	2.41	2.59	E2	4.80	5.00	5.20
A2	1.85	2.00	2.15	E3	2.30	2.50	2.70
b	1.11	1.21	1.36	e	5.44(BSC)		
b2	1.91	2.01	2.21	L	19.82	19.92	20.22
b4	2.91	3.01	3.21	L1	-	-	4.30
c	0.51	0.61	0.75	$\phi P$	3.40	3.60	3.80
D	20.80	21.00	21.30	$\phi P1$	-	-	7.30
D1	16.25	16.55	16.85	S	6.15(BSC)		
E	15.50	15.80	16.10	-	-	-	-

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